EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	0	"absoprtiong promiting layer"	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/03 07:57
L2	0	"absoprtion promiting layer"	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/03 07:57
L3	0	"adhesion promiting layer"	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/03 09:44
L4	3374	"adhesion promoting layer"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/03 09:44
L5	1805	"adhesion promoting layer" not @pd>"20031203"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/03 09:45
L6	1805	"adhesion promoting layer" not (@pd>"20031203" @ad>"20031203")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/03 09:45
L7	2353	"adhesion promoting layer" not (@ad>"20031203")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/03 09:46
L8	77	"adhesion promoting layer" same absorpt$ not (@ad>"20031203")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/03 09:46
L9	21	"adhesion promoting layer" same absorpt$ same (contact metal bump) not (@ad>"20031203")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/03 09:47
L10	0	absorpt? with large? with (metal? contact?) not (@ad>"20031203")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/03 11:45

L11	19	absorpt? with (metal? contact?) not (@ad>"20031203")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/03 11:45
L12	1701	absorpt? not (@ad>"20031203")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/03 11:46
L13	5	absorpt? with metal with surface not (@ad>"20031203")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/03 11:46
L14	11	absorpt? with layer with surface not (@ad>"20031203")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/03 11:47
L15	16598	absorpt$ with layer with surface not (@ad>"20031203")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/03 11:47
L16	1120	absorpt$ with layer with surface with metal not (@ad>"20031203")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/03 11:48
L17	12	absorpt$ with layer with surface with metal with larger not (@ad>"20031203")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/03 11:48
L18	1120	absorpt$ with layer with surface with metal not (@ad>"20031203")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/03 11:56
L19	202	absorpt$ with surface with metal with laser not (@ad>"20031203")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/03 11:56

L20	202	absorpt$ with surface with metal with laser same surface not (@ad>"20031203")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/03 11:56
L21	202	absorpt$ with surface with metal with laser same (surface area) not (@ad>"20031203")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/03 11:57
L22	1	larger with absorpt$ with surface with metal with laser same (surface area) not (@ad>"20031203")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/03 11:58
L23	1883	seal$3 with ring with sensor not @ad>"20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/03 13:18
L24	237	seal? with ring with sensor not @ad>"20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/03 13:19
L25	97	seal$3 with ring with sensor with surround$3 not @ad>"20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/03 13:19
L26	52	(seal$3 near2 ring) with sensor with surround$3 not @ad>"20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/03 16:24
L27	3	(seal$3 near2 ring) with sensor with surround$3 with (metal$5) not @ad>"20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/03 16:25
L28	0	("2004/0180464").URPN.	USPAT	OR	ON	2008/12/03 16:31
L29	12	("20010023087" | "20040007750" | "20040173913" | "20040266048" | "20050253240" | "20060006511" | "5811799" | "6140144" | "6316840" | "6323550" | "6432737" | "6674159").PN. OR ("7335971").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/03 16:34
S1	68034	wafer with contact$3 or bond $3 with diode with laser	US-PGPUB; USPAT; USOCR; EPO; DERWENT; IBM_TDB	OR	ON	2008/10/22 15:56
S2	257	wafer with (contact$3 or bond $3) with diode with laser	US-PGPUB; USPAT; USOCR; EPO; DERWENT; IBM_TDB	OR	ON	2008/10/22 15:56

S3	0	wafer with (contact$3 or bond $3) with diode with laser with ring	US-PGPUB; USPAT; USOCR; EPO; DERWENT; IBM_TDB	OR	ON	2008/10/22 15:56
S4	7	wafer with (contact$3 or bond $3) with diode with laser same metallization	US-PGPUB; USPAT; USOCR; EPO; DERWENT; IBM_TDB	OR	ON	2008/10/22 15:57
S5	21	wafer with (contact$3 or bond $3) with diode with laser same sensor	US-PGPUB; USPAT; USOCR; EPO; DERWENT; IBM_TDB	OR	ON	2008/10/22 15:58
S6	19	wafer with (contact$3 or bond $3) with component with radiation	US-PGPUB; USPAT; USOCR; EPO; DERWENT; IBM_TDB	OR	ON	2008/10/22 16:00
S7	0	("2007/0272991").URPN.	USPAT	OR	ON	2008/10/22 16:01
S8	1063	438/455.ccls.	USPAT	OR	ON	2008/10/22 16:08
S9	38	438/455.ccls. and (wafer with (contact$3 or bonding) with component)	USPAT	OR	ON	2008/10/22 16:09
S10	23	("4826787" | "5048744" | "5262347" | "5882992").PN. OR ("6118181").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/10/22 16:14
S11	26	("3967162" | "4116517" | "4769272" | "4857668" | "5142101" | "5262347" | "5397857" | "5474458" | "5508228" | "5835142" | "5854514" | "5938452" | "6005292" | "6046410" | "6090687" | "6092280" | "6096413" | "6118181" | "6249051" | "6266872" | "6358063" | "6365500" | "6451374" | "6580159" | "6713314" | "7005573").PN. OR ("7294919").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/10/22 16:21
S12	4	("5481082" or "5500540" "6062461" "20020115234"). pn.	US-PGPUB; USPAT; USOCR	OR	ON	2008/10/22 16:44
S13	2035	wafer with (contact$3 bond $3) with laser	US-PGPUB; USPAT; USOCR; EPO; DERWENT; IBM_TDB	OR	ON	2008/11/24 17:22

S14	33	wafer with (contact$3 bond $3) with laser with metallization	US-PGPUB; USPAT; USOCR; EPO; DERWENT; IBM_TDB	OR	ON	2008/11/24 17:22
S15	2890	257/414.ccls. or 438/455.ccls.	US-PGPUB; USPAT; USOCR; EPO; DERWENT; IBM_TDB	OR	ON	2008/11/24 17:25
S16	1094	257/414.ccls. or 438/455.ccls. and (wafter with laser)	US-PGPUB; USPAT; USOCR; EPO; DERWENT; IBM_TDB	OR	ON	2008/11/24 17:25
S17	1094	257/414.ccls. or 438/455.ccls. and (wafter with laser with contact)	US-PGPUB; USPAT; USOCR; EPO; DERWENT; IBM_TDB	OR	ON	2008/11/24 17:25
S18	1094	257/414.ccls. or 438/455.ccls. and (wafter with laser with metal$8)	US-PGPUB; USPAT; USOCR; EPO; DERWENT; IBM_TDB	OR	ON	2008/11/24 17:26
S19	1094	257/414.ccls. or 438/455.ccls. and (wafter with laser with radiation)	US-PGPUB; USPAT; USOCR; EPO; DERWENT; IBM_TDB	OR	ON	2008/11/24 17:26
S20	1094	257/414.ccls. or 438/455.ccls. and (wafter with laser with radiation) not @pd>"20031203"	US-PGPUB; USPAT; USOCR; EPO; DERWENT; IBM_TDB	OR	ON	2008/11/24 17:29
S21	0	(257/414.ccls. or 438/455. ccls.)and (wafter with laser with radiation) not @pd>"20031203"	US-PGPUB; USPAT; USOCR; EPO; DERWENT; IBM_TDB	OR	ON	2008/11/24 17:29
S22	0	(257/414.ccls.) and (wafter with laser with radiation) not @pd>"20031203"	US-PGPUB; USPAT; USOCR; EPO; DERWENT; IBM_TDB	OR	ON	2008/11/24 17:29
S23	0	("2007/0272991").URPN.	USPAT	OR	ON	2008/11/25 09:06

S24	31	("4489478"	"4612083"	"4931405"	"4956693"	"5283454"	"5355022"	"5412231"	"5453394"	"5619052"	"5622886"	"5744866"	"5755914"	"5783850"	"5856229"	"5863832"	"5877070"	"5966620"	"6057212"	"6110529"	"6118181"	"6136666"	"6150031"	"6183857"	"6312797"	"6313012").PN. OR ("6744116").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/25 09:07
S25	84	("3777281"	"4558346"	"4769272"	"5156322"	"5361967"	"5490628"	"5547093"	"5573171"	"5577656"	"5831162").PN. OR ("6062461").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/25 09:14
S26	164	("4400868"	"4552607").PN. OR ("4612083").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/25 09:20
S27	4007	(wafer or substrate) with (contact$3 or bond$3) with laser not @pd>"20030203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/25 09:26
S28	578	(wafer or substrate) with (contact$3 or bond$3) with laser with (metal or metallization) not @pd>"20030203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/25 09:26
S29	89	(wafer or substrate) with (contact$3 or bond$3) with laser with (metal or metallization) same diode not @pd>"20030203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/25 09:26
S30	43	(wafer or substrate) with (contact$3 or bond$3) with laser with (metal or metallization) same radiat$3 not @pd>"20030203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/25 09:29
S31	186	((wafer or substrate) with (contact$3 or bond$3) with laser with (metal or metallization)).clm.	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/25 09:35
S32	7	((wafer or substrate) with (contact$3 or bond$3) with laser with (metal or metallization) with radiation).clm.	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/25 09:35
S33	1	(wafer with components with contact with laser with radiation).clm.	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/25 09:36
S34	3	(wafer with components with contact with laser).clm.	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/25 09:36

S35	13	("20040232500" | "5229647" | "5355022" | "5545912" | "5929497" | "5939633" | "6118181" | "6236115" | "6239495" | "6323550" | "6448109" | "6505511" | "6744127").PN. OR ("7034393").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/25 09:44
S36	22	("3237272" | "3295089" | "3657611" | "3761783" | "4005454" | "4067104" | "4204628").PN. OR ("4257156").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/25 09:51
S37	4882	(wafer substrate) with (contact $3 or bond$3) with laser not @pd>"20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/25 09:53
S38	577	(wafer substrate) with (contact $3 or bond$3) with laser near3 diode not @pd>"20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/25 09:54
S39	140	(wafer substrate) with (contact $3 or bond$3) with laser near3 radiation not @pd>"20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/25 09:54
S40	40	azdasht-ghassem.in.	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/25 09:59
S41	15	("4119260" | "4906812" | "4970365" | "4978385" | "5055652" | "5250469" | "5341979" | "5354392" | "5360426" | "5847356" | "6323058").PN. OR ("6478906").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/25 10:02
S42	39	("4764804" | "4957882" | "4997791" | "5071787").PN. OR ("5250469").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/25 10:08
S43	50	zakel-elke.in.	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/25 10:12
S44	6	("3765938" | "3869787" | "4340167" | "5075253").PN. OR ("5976302").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/25 10:12
S45	4	("5861323" | "5895229" | "5977512" | "6181569").PN. OR ("6955943").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/25 10:14
S46	15	("4119260" | "4906812" | "4970365" | "4978385" | "5055652" | "5250469" | "5341979" | "5354392" | "5360426" | "5847356" | "6323058").PN. OR ("6478906").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/25 10:15
S47	0	438/455.ccls. same wafer	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/25 10:19

S48	1442	438/455.ccls. and wafer	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/25 10:19
S49	134	438/455.ccls. and (wafer with laser)	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/25 10:19
S50	49	438/455.ccls. and (wafer with laser) not @pd>"20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/25 10:19
S51	3	("4811062").PN. OR ("6479371").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/25 10:24
S52	97	("3407479" | "3457123" | "3471754" | "3689357" | "4051354" | "4292093" | "4305640" | "4604162" | "4663831" | "4673962" | "4761768" | "4766569" | "4920396" | "4948937" | "4962879" | "4987089" | "5001526" | "5017504" | "5021355" | "5028977" | "5097291" | "5102817" | "5110752" | "5156987" | "5177028" | "5202278" | "5208657" | "5223081" | "5234535" | "5266514" | "5320880" | "5327380" | "5376575" | "5391911" | "5392245" | "5393704" | "5396093" | "5410169" | "5414287" | "5416041" | "5421953" | "5422499" | "5438009" | "5440158" | "5441591" | "5445986" | "5455445" | "5460316" | "5460988" | "5466625" | "5483094" | "5483487" | "5492853" | "5495441" | "5497017" | "5504357" | "5508219" | "5508542" | "5528062" | "5593912" | "5616934" | "5640342" | "5644540" | "5646900" | "5691230" | "5710057" | "6027960" | "6093623").PN. OR ("6423613").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/25 10:26
S53	6	("3765938" | "3869787" | "4340167" | "5075253").PN. OR ("5976302").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/25 10:27
S54	0	("2007/0272991").URPN.	USPAT	OR	ON	2008/11/25 10:29
S55	682	laser near1 diode with heat with (wafer substrate)	US-PGPUB; USPAT; USOCR; EPO; DERWENT; IBM_TDB	OR	ON	2008/11/25 15:41

S56	238	laser near1 diode with (heat thermal) with (wafer substrate) with (contact$3 bond$3)	US-PGPUB; USPAT; USOCR; EPO; DERWENT; IBM_TDB	OR	ON	2008/11/25 15:41
S57	5	laser near1 diode with (heat thermal) with (wafer substrate) with (contact$3 bond$3) same arrangement	US-PGPUB; USPAT; USOCR; EPO; DERWENT; IBM_TDB	OR	ON	2008/11/25 15:41
S58	88	laser near1 diode with (heat thermal) with (wafer substrate) with (contact$3 bond$3) not @pd>"20031203"	US-PGPUB; USPAT; USOCR; EPO; DERWENT; IBM_TDB	OR	ON	2008/11/25 15:43
S59	1	laser near1 diode with (heat thermal) with (wafer substrate) same matrix	US-PGPUB; USPAT; USOCR; EPO; DERWENT; IBM_TDB	OR	ON	2008/11/25 15:47
S60	7	(laser near1 diode) with (wafer substrate) same matrix same arrangement	US-PGPUB; USPAT; USOCR; EPO; DERWENT; IBM_TDB	OR	ON	2008/11/25 15:48
S61	256	438/455.ccls. and laser and emit$4	US-PGPUB; USPAT; USOCR; EPO; DERWENT; IBM_TDB	OR	ON	2008/11/25 15:49
S62	102	438/455.ccls. and laser and emit$4 and radiat$3	US-PGPUB; USPAT; USOCR; EPO; DERWENT; IBM_TDB	OR	ON	2008/11/25 15:49
S63	32	438/455.ccls. and laser and emit$4 and radiat$3 not @pd>"20031203"	US-PGPUB; USPAT; USOCR; EPO; DERWENT; IBM_TDB	OR	ON	2008/11/25 15:54
S64	19	("20020062787" | "4375018" | "4729640" | "4732599" | "4824073" | "4911968" | "5146671" | "5340978" | "5629787" | "5677749" | "5751492" | "5886971" | "5981945" | "6059188" | "6122009" | "6304243" | "6613443" | "6627814").PN. OR ("6893941").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/25 15:55

S65	19	("20020062787"	"4375018"	"4729640"	"4732599"	"4824073"	"4911968"	"5146671"	"5340978"	"5629787"	"5677749"	"5751492"	"5886971"	"5981945"	"6059188"	"6122009"	"6304243"	"6613443"	"6627814").PN. OR ("6893941").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/25 16:43
S66	29	("20020036055"	"20020149296"	"4233477"	"4237399"	"4670682"	"4991283"	"5248912"	"5430344"	"5486494"	"5585136"	"5691593"	"5869189"	"5950291"	"6071795"	"6262516"	"6335263"	"6370964"	"6408513"	"6476540"	"6645830"	"6666943"	"6715192"	"6771007").PN. OR ("7118990").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/25 16:45
S67	6	("20020096994"	"20030087476"	"4808983"	"5459081").PN. OR ("7169652").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/25 16:47
S68	1	"7157352".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/25 16:49
S69	97	("3407479"	"3457123"	"3471754"	"3689357"	"4051354"	"4292093"	"4305640"	"4604162"	"4663831"	"4673962"	"4761768"	"4766569"	"4920396"	"4948937"	"4962879"	"4987089"	"5001526"	"5017504"	"5021355"	"5028977"	"5097291"	"5102817"	"5110752"	"5156987"	"5177028"	"5202278"	"5208657"	"5223081"	"5234535"	"5266514"	"5320880"	"5327380"	"5376575"	"5391911"	"5392245"	"5393704"	"5396093"	"5410169"	"5414287"	"5416041"	"5421953"	"5422499"	"5438009"	"5440158"	"5441591"	"5445986"	"5455445"	"5460316"	"5460988"	"5466625"	"5483094"	"5483487"	"5492853"	"5495441"	"5497017"	"5504357"	"5508219"	"5508542"		US-PGPUB; USPAT; USOCR	OR	ON	2008/11/25 16:51

		"5528062" | "5593912" | "5616934" | "5640342" | "5644540" | "5646900" | "5691230" | "5710057" | "6027960" | "6093623").PN. OR ("6423613").URPN.				
S70	3	("4811062").PN. OR ("6479371").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/25 16:54
S71	39	("4764804" | "4957882" | "4997791" | "5071787").PN. OR ("5250469").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/25 16:55
S72	148	laser near3 treatment near2 diode	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/25 16:58
S73	2	(laser near3 treatment near2 diode) with activat$3	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/25 16:58
S74	0	(laser near3 treatment near2 diode) same arrangment	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/25 16:59
S75	62	(laser near3 treatment near2 diode) not @pd>"20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/25 16:59
S76	0	(laser near3 treatment with diode) same matrix not @pd>"20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/25 17:02
S77	11	(laser near3 treatment with diode) and matrix not @pd>"20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/25 17:02
S78	473	(laser near3 diode) with activat $3 with emit4	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/26 07:55
S79	17	(laser near3 diode) with activat $3 with emit4 same treatment	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/26 07:55
S80	39	("4764804" | "4957882" | "4997791" | "5071787").PN. OR ("5250469").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/26 08:00
S81	236	(laser near3 diode) with activat $3 with emit4 not @pd>"20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/26 08:03
S82	4	"438".clas. and (laser near3 diode) with activat$3 with emit $4 not @pd>"20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/26 08:05
S83	39	(laser near3 diode) with activat $3 with (individual or group) not @pd>"20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/26 08:07
S84	2	(laser near3 diode) with activat $3 with (individual or group) same (heat or thermal) not @pd>"20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/26 08:08
S85	10898	laser with treatment not @pd>"20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/26 08:09
S86	283	laser with treatment with diode not @pd>"20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/26 08:09
S87	1	laser with treatment with diode with activate not @pd>"20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/26 08:10

S88	2	("5936986" | "6044095").PN. OR ("6385221").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/26 08:12
S89	1	laser with diode with arrangment	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/26 08:17
S90	0	diode near2 laser near2 treatment near3 arrangement	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/26 08:18
S91	121	diode near2 laser near2 treatment	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/26 08:18
S92	3	diode near2 laser near2 treatment same (wafter substrate)	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/26 08:18
S93	849	laser with radiation with diode same (wafter substrate)	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/26 08:20
S94	412	laser with radiation with diode same (wafter substrate) not @pd> "20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/26 08:20
S95	6	laser with radiation with diode same activat$3 same (wafter substrate) not @pd> "20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/26 08:20
S96	11	("3463898" | "4357072" | "4854667" | "4946246" | "4970365" | "5178723" | "5421506").PN. OR ("5938951").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/26 08:21
S97	412	laser with radiation with diode same (wafter substrate) not @pd> "20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/26 08:22
S98	1	treatment with laser with radiation with diode same (wafter substrate) not @pd> "20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/26 08:22
S99	1075	257/414.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/26 08:23
S100	239	257/414.ccls. and laser	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/26 08:23
S101	77	257/414.ccls. and laser not @pd> "20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/26 08:23
S102	22	("3791863" | "3900940" | "4353957" | "4412377" | "4483751" | "4882455" | "5246782" | "5501744" | "5686172" | "5910336" | "5942048" | "6084176" | "6369934").PN. OR ("6653701").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/26 08:24
S103	283	laser with (ablaltion or treatment) with diode not @pd> "20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/26 08:25
S104	181	laser with (ablaltion or treatment) with diode and contact$3 not @pd> "20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/26 08:25

S105	35	("257" or "438").clas. and laser with (ablation or treatment) with diode and contact$3 not @pd>"20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/26 08:26
S106	40	("257" or "438").clas. and laser with (ablation or treatment) with diode not @pd>"20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/26 08:27
S107	23	("5247533" | "5272108" | "5290393" | "5306662" | "5389571").PN. OR ("5496766").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/26 08:27
S108	28	("5141894" | "5496766" | "5598014" | "5689123" | "5932896").PN. OR ("6113685").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/26 08:29
S109	31	("20020048905" | "20020078559" | "20020088985" | "20020113284" | "20020115265" | "20020137342" | "20030087476" | "5177405" | "5206749" | "5258320" | "5438241" | "5593917" | "5739800" | "5766695" | "5834327" | "5981977" | "6113685" | "6117704" | "6274518" | "6287891" | "6303405" | "6403985" | "6413838" | "6420242" | "6425971" | "6559905" | "6589814" | "6613610" | "6636185" | "6656819" | "6683416").PN. OR ("7233030").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/26 08:31
S110	1806	438/455.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/26 08:37
S111	23	438/455.ccls. and (diode with plurality)	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/26 08:37
S112	1582	"laser radiation" with diode	US-PGPUB; USPAT; USOCR; EPO; DERWENT; IBM_TDB	OR	ON	2008/11/26 08:59
S113	890	"laser radiation" with diode not @pd>"20031203"	US-PGPUB; USPAT; USOCR; EPO; DERWENT; IBM_TDB	OR	ON	2008/11/26 08:59
S114	29	"laser radiation" with diode with plurality not @pd>"20031203"	US-PGPUB; USPAT; USOCR; EPO; DERWENT; IBM_TDB	OR	ON	2008/11/26 08:59

S115	51	("2379790" | "2403685" | "2758510" | "2869010" | "3245002" | "3248670" | "3283207" | "3284722" | "3289101" | "3300671" | "3303432" | "3349174" | "3359507" | "3359509" | "3361988" | "3396344" | "3417246" | "3429733" | "3431437" | "3431512" | "3471923" | "3492549").PN. OR ("3614661").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/26 09:05
S116	3812	(diode with (linear or parallel) with plurality) not @pd>"20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/26 09:09
S117	1061	(diode with (linear or parallel) with plurality) and (substrate wafer) not @pd>"20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/26 09:09
S118	0	(diode with (linear or parallel) with plurality) and albalation and (substrate wafer) not @pd>"20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/26 09:09
S119	632	(diode with (linear or parallel) with plurality) and light and (substrate wafer) not @pd>"20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/26 09:09
S120	38	(diode with (linear or parallel) with plurality with arrangement) and light and (substrate wafer) not @pd>"20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/26 09:11
S121	22	("3835414" | "4319839" | "4358659" | "4471415" | "4562350" | "4601452" | "4687165" | "4720168" | "4901325" | "4959761" | "4993801").PN. OR ("5617441").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/26 09:13
S122	27	(laser near2 array near2 diode) with equivalent not @pd>"20031203"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/26 10:31
S123	7	(laser near2 array near2 diode) with equivalent and Yag not @pd>"20031203"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/26 10:36
S124	4	"6611540" or "7016383"	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/26 10:37
S125	1	"7456371"	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/26 10:40

S126	6	438/487.ccls. and (laser near2 array) not @pd>"20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/26 10:41
S127	14	438/487,455.ccls. and (laser near2 array) not @pd>"20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/26 10:45
S128	194	(438/487,455.ccls. or "219". clas.)and (laser near2 array) not @pd>"20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/26 10:46
S129	194	(438/487,455.ccls. or "219". clas.) and (laser near2 array) not @pd>"20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/26 10:46
S130	11	("4341569" | "5013670" | "5358925" | "5366926" | "5407845").PN. OR ("5821135").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/26 10:48
S131	49	laser near2 welding near4 semiconductor not @pd>"20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/26 10:54
S132	19494	laser near2 beam near2 (radiat $3 or irradiat$3) not @pd>"20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/26 11:02
S133	122	laser near2 beam near2 (radiat $3 or irradiat$3) same diode same (thermal heat$3 anneal $3) not @pd>"20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/26 11:03
S134	9	("4821051" | "5032960" | "5191481" | "5271079").PN. OR ("5412509").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/26 11:07
S135	56	("20020048864" | "20030003636" | "20030119286" | "20030203656" | "20070202668" | "4020319" | "4069080" | "4174476" | "4234356" | "4576436" | "4659422" | "4925273" | "5048946" | "5219786" | "5325381" | "5422758" | "5515194" | "5517768" | "5612251" | "5767003" | "5798867" | "5854803" | "5897799" | "5900980" | "5910262" | "5923966" | "5948291" | "5952058" | "6020045" | "6038075" | "6080643" | "6087625" | "6091047" | "6117752" | "6171890" | "6210996" | "6229639" | "6242291" | "6266167" | "6300176" | "6322625" | "6426245" | "6468842" | "6548370" | "6555449" | "6599788" | "6632711" | "6657154" | "6730550" | "6753212" | "6835675" | "6927109" |	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/26 11:08

		"6974731" | "7029996" | "7179698" | "7319056").PN. OR ("7456371").URPN.				
S136	1300	semiconductor near2 laser near2 diode with beam not @pd>"20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/26 11:20
S137	2359310	semiconductor near2 laser near2 diode with beam same yagnot @pd>"20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/26 11:20
S138	31	semiconductor near2 laser near2 diode with beam same yag not @pd>"20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/26 11:20
S139	4	(laser near2 diode) with mov $3 same parallel same substrate not @pd>"20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/26 13:03
S140	17	("4318058" | "4884015" | "5343546" | "5511140" | "5537504" | "5546487" | "5579422" | "5602955" | "5610395" | "5611008").PN. OR ("5870517").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/26 13:04
S141	2	(laser near2 diode near2 array) with mov$3 same parallel not @pd>"20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/26 13:05
S142	92	(laser near2 diode near2 array) with mov$3 and (wafer substrate) not @pd>"20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/26 13:06
S143	535	(laser near2 diode near2 array) same (wafer substrate) not @pd>"20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/26 13:09
S144	46	(laser near2 diode near2 array) same (wafer substrate) same (mov$3 shift$3) not @pd>"20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/26 13:09
S145	10	(laser near2 diode near2 array) same beam same parallel same mov$3 not @pd>"20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/26 13:12
S146	22	(yag with laser) with semiconductor with mov$3	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/26 13:13
S147	85	("3848104" | "4046618" | "4059461" | "4083272" | "4160263" | "4234358" | "4249960" | "4309225" | "4328553" | "4341569" | "4370175" | "4385937" | "4439245" | "4463028" | "4468551" | "4469551" | "4545823" | "4722879" | "4724466" | "4727044" | "4734550" | "4764485" | "4803528" | "4805000" | "4835704" | "4862227" |	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/26 13:17

		"4876582" | "4885260" | "4937618" | "4943837" | "4956539" | "4970366" | "5004889" | "5122223" | "5141885" | "5145808" | "5217921" | "5219786" | "5221365" | "5231297" | "5241211" | "5252502" | "5264072" | "5272355" | "5288684" | "5289030" | "5304357" | "5308998" | "5313076" | "5348897" | "5348903" | "5352291" | "5365875" | "5372089" | "5372836" | "5413958" | "5424244" | "5455430" | "5477073" | "5533040" | "5545571" | "5561081" | "5578520" | "5612251" | "5622814" | "5643801" | "5648277" | "5696003" | "5712191" | "5756364" | "5849043" | "5858473" | "5891764" | "5897799" | "5962897" | "5968383" | "5977559" | "6002101" | "6031290" | "6080643" | "6087277" | "6204099" | "6358784" | "6586346" | "6784530").PN. OR ("7179726").URPN.				
S148	0	(yag with laser) with semiconductor with mov$3 same distance	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/26 13:47
S149	148	(yag with laser) same mov$3 same distance	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/26 13:48
S150	92	(yag with laser) same mov$3 same distance not @pd>"20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/26 13:48
S151	476	(diode near2 laser) same mov$3 same distance not @pd>"20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/26 13:53
S152	0	(diode near2 laser near2 aray) same mov$3 same distance not @pd>"20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/26 13:53
S153	14	(diode near2 laser near2 array) same mov$3 same distance not @pd>"20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/26 13:53
S154	2	(wafer substrate) with frame with clamp$3 with laser not @pd>"20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/26 14:03
S155	10	("4412133" | "4724222" | "4742376" | "5142154" | "5152707" | "5227606" | "5374829" | "5471279").PN. OR ("5905566").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/26 14:07

S156	6	(wafer substrate) and (frame with clamp$3 with laser) not @pd>"20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/26 14:08
S157	34	(wafer substrate) and (frame with clamp$3 with laser)	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/26 14:10
S158	59	(wafer substrate) and (frame with (clamp$3 hold$3) with laser) and sensor	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/26 14:13
S159	28	(wafer substrate) same (frame with (clamp$3 hold$3) with laser) and sensor	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/26 14:13
S160	7	(wafer substrate) same pressure same (frame with (clamp$3 hold$3) same laser) and sensor	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/26 14:30
S161	12	("20020029639" | "20030217915" | "5483095" | "5895233" | "6229190" | "6335559" | "6346742" | "6521477").PN. OR ("6762072").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/26 14:34
S162	25	wafer with (laser near2 diode) with sens$3	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/01 09:18
S163	770	(laser near2 diode) with sens $3 with temperature	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/01 09:20
S164	153	(laser near2 diode) with sens $3 with temperature same beam	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/01 09:20
S165	91	(laser near2 diode) with sens $3 with temperature same beam not @pd>"20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/01 09:21
S166	12	("20020029639" | "20030217915" | "5483095" | "5895233" | "6229190" | "6335559" | "6346742" | "6521477").PN. OR ("6762072").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/01 09:27
S167	13	("20040135510" | "20050236161" | "4405875" | "4687264" | "5810332" | "5977668" | "6119920" | "6194250" | "6762072" | "6775958" | "6962834" | "6981806" | "7176555").PN. OR ("7241966").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2004/12/01 09:27
S168	10	("4412133" | "4724222" | "4742376" | "5142154" | "5152707" | "5227606" | "5374829" | "5471279").PN. OR ("5905566").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/01 09:28
S169	602103	YAG laser	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/01 09:35
S170	12	(YAG laser) with wafer with bonding with sensor	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/01 09:35

S171	6348	positioning with device with substrate	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/01 10:48
S172	257	positioning with device with substrate with bonding	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/01 10:49
S173	132	positioning with device with substrate with bonding not @pd> "20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/01 10:50
S174	2365447	positioning with device with substrate with bonding with alignmentnot @pd> "20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/01 10:50
S175	17	positioning with device with substrate with bonding with alignment not @pd> "20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/01 10:50
S176	238	positioning with device with substrate with alignment not @pd> "20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/01 10:51
S177	4	("5481082" or "5500540" or "6062461" or "20020115234"). pn.	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/01 15:02
S178	74	("4698662" | "4862231" | "5075253" | "5214845" | "5244818" | "5266794" | "5283447" | "5287001" | "5291064").PN. OR ("5500540").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/01 15:34
S179	36	laser near2 diode with sens$3 with transparent	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/01 16:18
S180	15	laser near2 diode with sens$3 with transparent not @pd> "20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/01 16:18
S181	294	position$3 with triaxial not @pd> "20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/01 17:10
S182	59	position$3 with (triaxial or biaxial) same pressure not @pd> "20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/01 17:10
S183	2	position$3 with plane with (triaxial or biaxial) same pressure not @pd> "20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/01 17:11
S184	63	plane with (triaxial or biaxial) same pressure not @pd> "20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/01 17:13
S185	9	plane with (triaxial or biaxial) same wafer not @pd> "20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/01 17:14
S186	8	(mov$3 or position$3) with (triaxial) same wafer not @pd> "20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/01 17:15
S187	362	(mov$3 or position$3) with (triaxial) not @pd> "20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/01 17:17

S188	30	plane with (mov$3 or position $3) with (triaxial) not @pd> "20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/01 17:17
S189	78	(triaxial) with (wafer substrate) not @pd> "20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/01 17:19
S190	1313	257/727	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/01 17:25
S191	882	257/727.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/01 17:25
S192	696	257/727.ccls. not @pd> "20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/01 17:26
S193	100	257/727.ccls. and wafer not @pd> "20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/01 17:27
S194	0	257/727.ccls. and wafer and triaxial not @pd> "20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/01 17:27
S195	0	257/727.ccls. and triaxial not @pd> "20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/01 17:27
S196	0	257/727.ccls. and (biaxial triaxial) not @pd> "20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/01 17:28
S197	245	257/727.ccls. and (wafer substrate) not @pd> "20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/01 17:30
S198	86	257/727.ccls. and (wafer substrate) with (mov$3 or position$3) not @pd> "20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/01 17:31
S199	12	257/727.ccls. and (wafer substrate) with (mov$3) not @pd> "20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/01 17:33
S200	12	("20020029639" | "20030217915" | "5483095" | "5895233" | "6229190" | "6335559" | "6346742" | "6521477").PN. OR ("6762072").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/02 09:08
S201	7	("5243861" | "5837562" | "6400009" | "6762072" | "6777259").PN. OR ("6953993").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/02 09:10
S202	0	(rear near$2 contact) with sensore with cohesive	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/02 09:12
S203	0	(rear near$2 contact) with sensore with transparent	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/02 09:12
S204	1531	(rear near$2 contact) with sensor with transparent	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/02 09:13
S206	0	(rear near$2 contact) with sensor with transparent with cohesive	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/02 09:13
S207	65	(rear near$2 contact) with sensor with transparent and MEM	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/02 09:13

S208	14768	sensor with contact with through	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/02 09:16
S209	218	sensor with contact with through with transparent	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/02 09:17
S210	114	sensor with contact with through with transparent not @pd>"20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/02 09:17
S211	238	contact$3 with wafer with transparent not @pd>"20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/02 09:45
S212	1	contact$3 with wafer with transparent with solder not @pd>"20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/02 09:45
S213	16	contact$3 with wafer with transparent same sensor not @pd>"20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/02 09:46
S214	107	contact$3 with wafer with transparent and sensor not @pd>"20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/02 09:48
S215	39	contact$3 with wafer with transparent with (through hole) not @pd>"20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/02 10:26
S216	34358	conduct$3 with adhesive not @pd>"20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/02 11:09
S217	34358	conduct$3 with adhesive not @pd>"20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/02 11:10
S218	8868	conduct$3 with adhesive with bond$3 not @pd>"20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/02 11:10
S219	325	conduct$3 with adhesive with (bond$3 contact$3) same wafer not @pd>"20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/02 11:11
S220	8	conduct$3 with adhesive with (bond$3 contact$3) same laser same wafer not @pd>"20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/02 11:12
S221	315	conduct$3 with adhesive with (bond$3 contact$3) same laser not @pd>"20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/02 11:13
S222	453	conduct$3 with absorpt$3 with laser not @pd>"20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/02 11:18
S223	87	conduct$3 with absorpt$3 with laser with material not @pd>"20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/02 11:18
S224	3913	conduct$3 near2 adhesive with contact$3 not @pd>"20031203"	US-PGPUB; USPAT; USOCR; EPO; DERWENT; IBM_TDB	OR	ON	2008/12/02 11:26

S225	611	conduct$3 near2 adhesive with contact$3 and wafer not @pd>"20031203"	US-PGPUB; USPAT; USOCR; EPO; DERWENT; IBM_TDB	OR	ON	2008/12/02 11:26
S226	111	conduct$3 near2 adhesive with contact$3 same wafer not @pd>"20031203"	US-PGPUB; USPAT; USOCR; EPO; DERWENT; IBM_TDB	OR	ON	2008/12/02 11:26
S227	0	conduct$3 near2 adhesive with contact$3 with (laser near2 diode) same wafer not @pd>"20031203"	US-PGPUB; USPAT; USOCR; EPO; DERWENT; IBM_TDB	OR	ON	2008/12/02 11:27
S228	2	conduct$3 near2 adhesive with contact$3 with (laser) same wafer not @pd>"20031203"	US-PGPUB; USPAT; USOCR; EPO; DERWENT; IBM_TDB	OR	ON	2008/12/02 11:27
S229	31	conduct$3 near2 adhesive with contact$3 with laser not @pd>"20031203"	US-PGPUB; USPAT; USOCR; EPO; DERWENT; IBM_TDB	OR	ON	2008/12/02 11:36
S230	97	("4505799" | "4996587" | "5063177" | "5107328" | "5123850" | "5138434" | "5155067" | "5229647" | "5266912" | "5334857" | "5384689" | "5444296" | "5468999" | "5474957" | "5517125" | "5562971" | "5633530" | "5646828" | "5674785" | "5677566" | "5689091" | "5696033" | "5723900" | "5739585" | "5753857" | "5763939" | "5789803" | "5796038" | "5811579" | "6013948" | "6020629" | "6072323" | "6094058" | "6097087" | "6107109" | "6180881" | "6235554" | "6271056" | "6294837" | "6303981" | "6404044").PN. OR ("6501165").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/02 11:39
S231	1335	conduct$3 with absorbent with material not @pd>"20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/02 14:58
S232	33	adhes$3 with conduct$3 with absorbent with material not @pd>"20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/02 14:59
S233	197	adhes$3 with conduct$3 with absor$4 with material not @pd>"20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/02 15:00

S234	203	adhes$3 with conduct$3 with absor$4 with layer not @pd>"20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/02 15:00
S235	49	adhes$3 with conduct$3 with absor$4 with layer with (wafer substrate) not @pd>"20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/02 15:01
S236	47	adhes$3 with conduct$3 with absor$4 with layer with (contact bump metal) not @pd>"20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/02 15:03
S237	8	("5162087" | "5179460" | "5525838" | "5651179" | "5670826" | "6207550" | "6264785").PN. OR ("6569512").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/02 15:05
S238	28	adhes$3 with conduct$3 with (absor$4 near2 material) with layer not @pd>"20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/02 15:08
S239	453	adhes$3 with conduct$3 with ((absor$4 near2 material) chromium) not @pd>"20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/02 15:10
S240	0	adhes$3 with conduct$3 with ((absor$4 near2 material) chromium) same (laser near2 diode) not @pd>"20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/02 15:10
S241	35	adhes$3 with conduct$3 with ((absor$4 near2 material) chromium) same (transparent) not @pd>"20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/02 15:10
S242	36	adhes$3 with conduct$3 with ((absor$4 near2 material) chromium) same (irradiation laser beam energery) not @pd>"20031203"	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/02 15:14

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